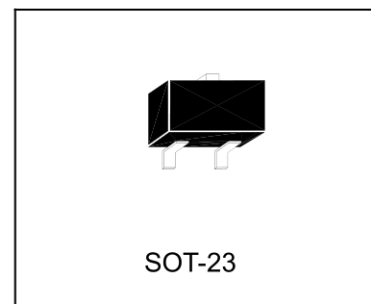




Adjustable Precision Shunt Regulators

WO764PNQ6



Description

The WO764PNQ6 series are three-terminal adjustable regulators with guaranteed thermal stability over applicable temperature range. The output voltage may be set to any value between V_{REF} (approximately 2.495 volts) and 36 volts with two external resistors. These devices have a typical dynamic output impedance of 0.1Ω . Active output circuitry provides a very sharp turn-on characteristic, making these devices excellent replacement for zener diodes in many applications.

Features

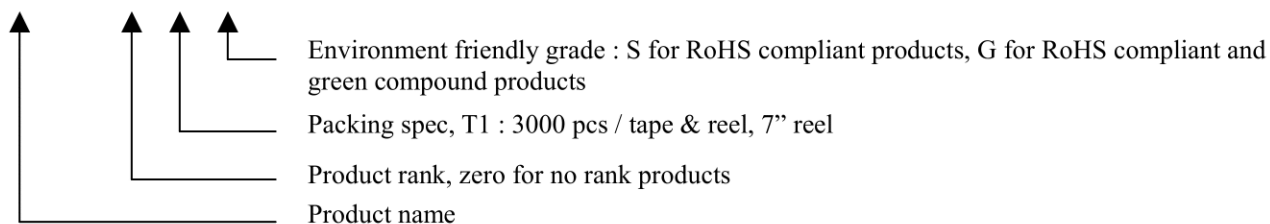
- Programmable output voltage
- Temperature coefficient is 50ppm/°C typical
- Improved temperature compensation
- Sink current capability of 0.1mA to 100mA
- Low output noise voltage
- Fast turn on response
- Heat Resistance, Soldering iron : 300°C, 5 seconds
- Low dynamic output impedance 0.1Ω (typ.)
- Electrostatic discharge voltage 2.5kV.
- Pb-free lead plating and halogen-free package

Classification

Rank	A	B	C
V_{REF}	$2.495\pm0.5\%$	$2.495\pm1\%$	$2.495\pm2\%$

Ordering Information

Device	Package	Shipping
WO764PNQ6- X - T1 - G	SOT-23 (Pb-free lead plating and halogen-free package)	3000 pcs / tape & reel





Absolute Maximum Ratings (Over operating free-air temperature range, unless otherwise specified)

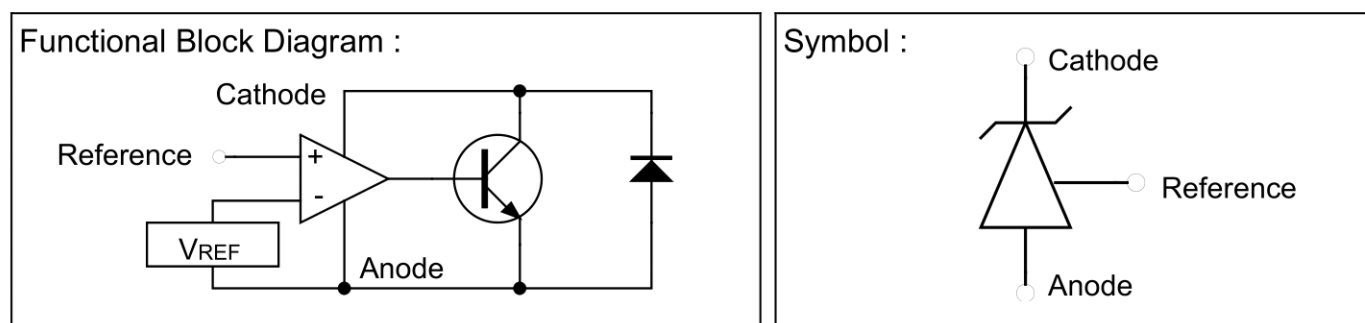
Characteristics	Symbol	Value	Unit
Cathode Voltage	V_{KA}	40	V
Cathode Current Range (Continuous)	I_K	-100~+150	mA
Reference Input Current Range	I_{REF}	-0.05~+10	mA
Power Dissipation	P_D	300	mW
Operating Free-air Temperature Range	T_j	-40~+125	°C
Lead Temperature (1.6mm aside from the case, 10s)	T_L	260	°C
ESD(HBM)	V_{ESD}	2500	V
Storage Temperature Range	T_{stg}	-65~+150	°C

Thermal Data

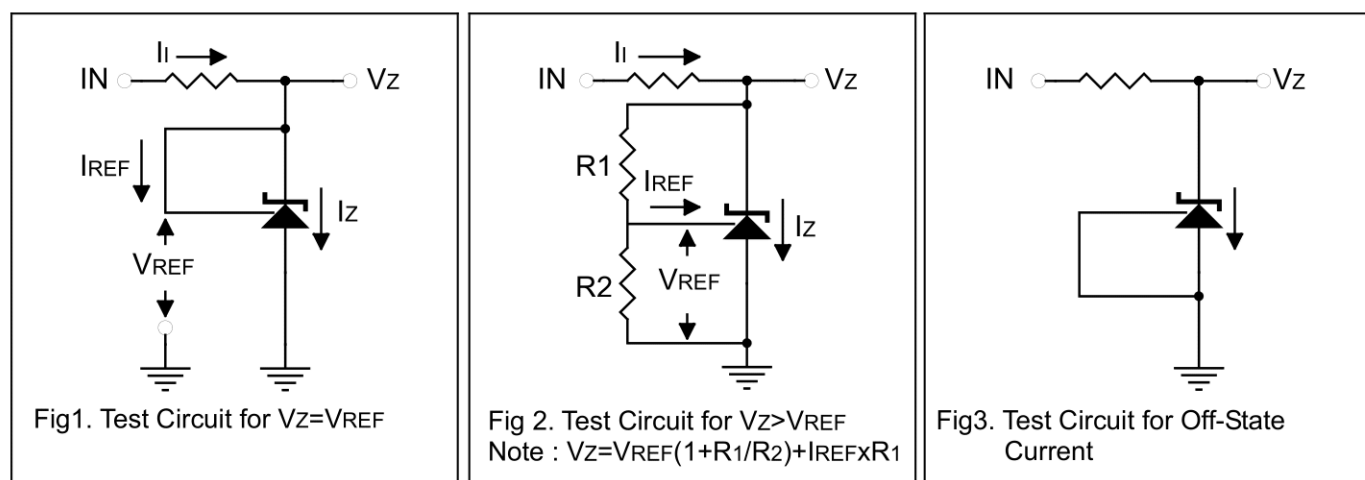
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	50	°C/W
Thermal Resistance, Junction-to-ambient, max (Note)	$R_{th,j-a}$	416	

Note: When mounted on FR-4 PCB with area measuring 10×10 mm

Functional Block Diagram & Symbol



Test Circuits

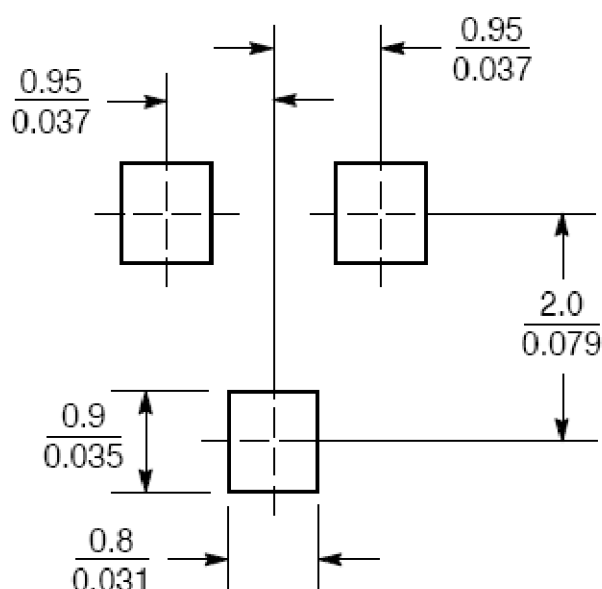




Electrical Characteristics ($T_a=25^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Conditions	Min	Typ	Max	Unit	Test Circuit
Reference Input Voltage	A-rank B-rank C-rank	$V_{KA}=V_{REF}, I_K=10\text{mA}$	2.480	2.495	2.510	V	1
			2.470	2.495	2.520		
			2.445	2.495	2.545		
Deviation of Reference Input Voltage Over Full Temperature Range	$V_{REF(dev)}$	$V_{KA}=V_{REF}, I_K=10\text{mA}$ $0 \leq T_a \leq 125^{\circ}\text{C}$	-	8	17	mV	1
Ratio of Change in Reference Input Voltage to the Change in Cathode Voltage	$\Delta V_{REF} / \Delta V_{KA}$	$I_K=10\text{mA},$ $\Delta V_{KA}=10\text{V to } V_{REF}$	-	-1.0	-2.7	mV/V	2
		$I_K=10\text{mA},$ $\Delta V_{KA}=36\text{V to } 10\text{V}$	-	-0.4	-2.0	mV/V	2
Reference Input Current	I_{REF}	$I_K=10\text{mA}, R_1=10\text{k}\Omega,$ $R_2=\infty$	-	0.5	1.2	μA	2
Deviation of Reference Input Current Over Full Temperature Range	$I_{REF(dev)}$	$I_K=10\text{mA}, R_1=10\text{k}\Omega,$ $R_2=\infty, T_a=\text{Full Range}$	-	0.4	1.2	μA	2
Minimum Cathode Current for Regulation	$I_{K(min)}$	$V_{KA}=V_{REF}$	-	0.04	0.3	mA	1
Off-State Cathode Current	$I_{K(off)}$	$V_{KA}=36\text{V}, V_{REF}=0\text{V}$	-	0.01	0.8	μA	3
Dynamic impedance	Z_{KA}	$V_{KA}=V_{REF}, f \leq 1.0\text{KHz}$ $I_K=0.2 \text{ to } 100\text{mA}$	-	0.1	0.37	Ω	1

Recommended Soldering Footprint

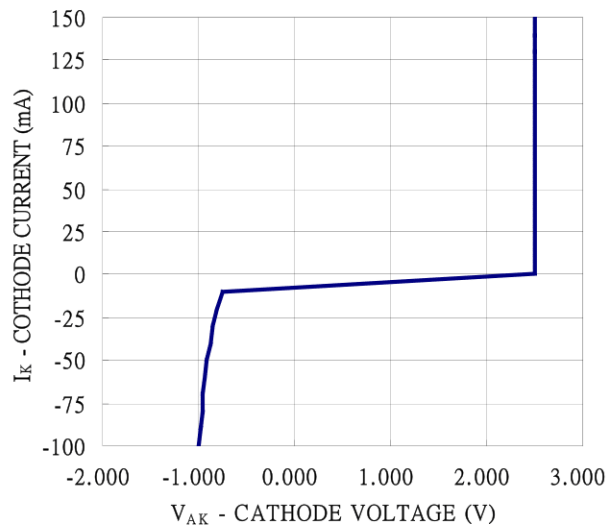


Unit : $\frac{\text{mm}}{\text{inches}}$

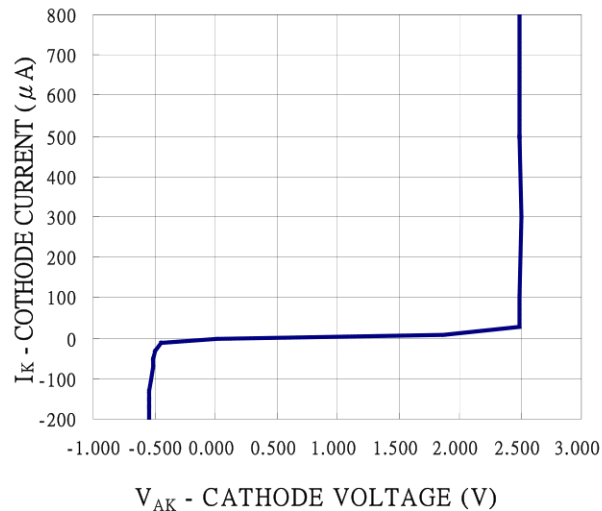


Typical Characteristics

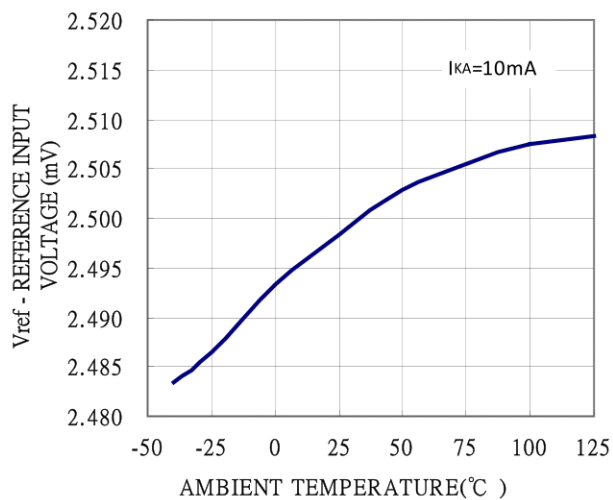
CATHODE CURRENT vs CATHODE VOLTAGE



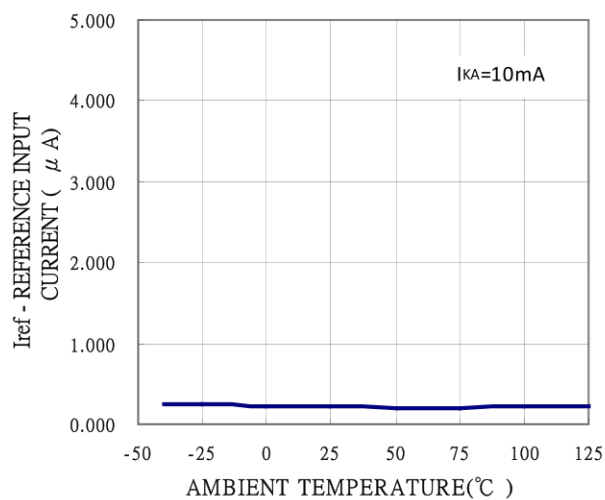
CATHODE CURRENT vs CATHODE VOLTAGE



REFERENCE INPUT VOLTAGE vs AMBIENT TEMPERATURE



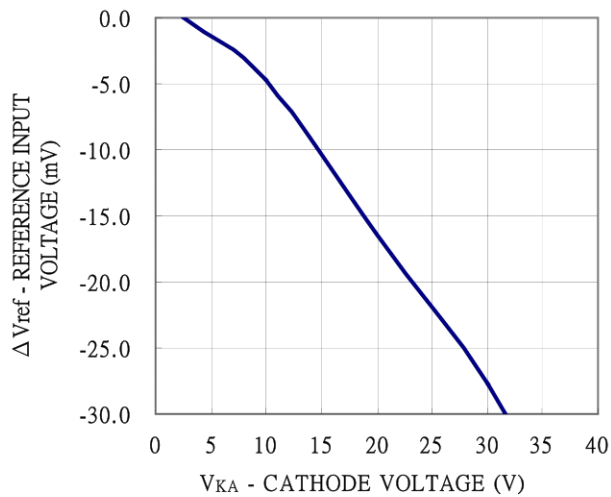
REFERENCE INPUT CURRENT vs AMBIENT TEMPERATURE



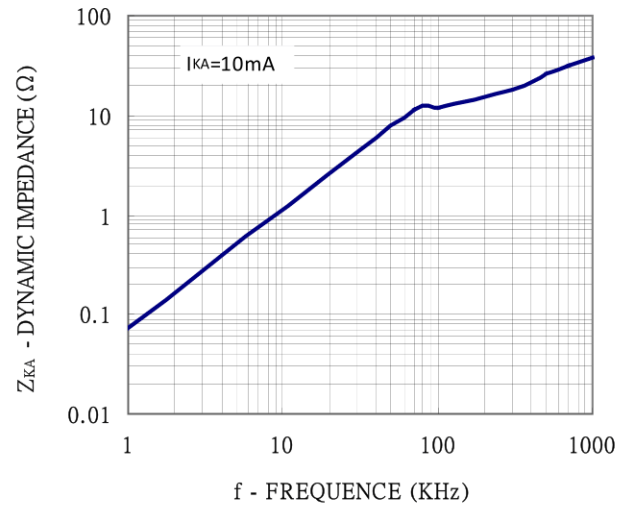


Typical Characteristics(Cont.)

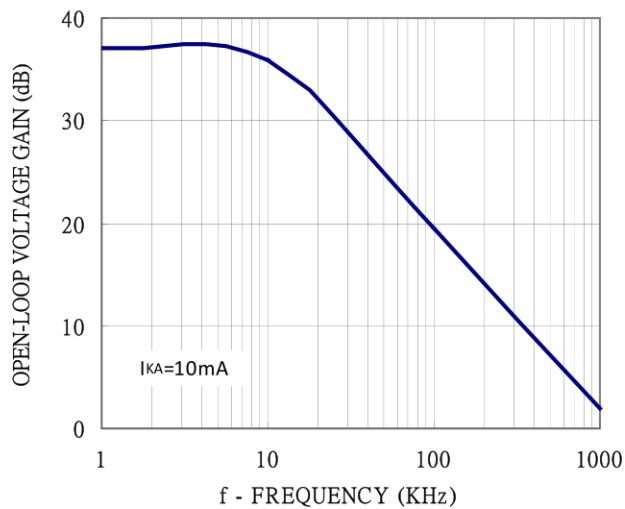
CATHODE VOLTAGE vs REFERENCE INPUT VOLTAGE



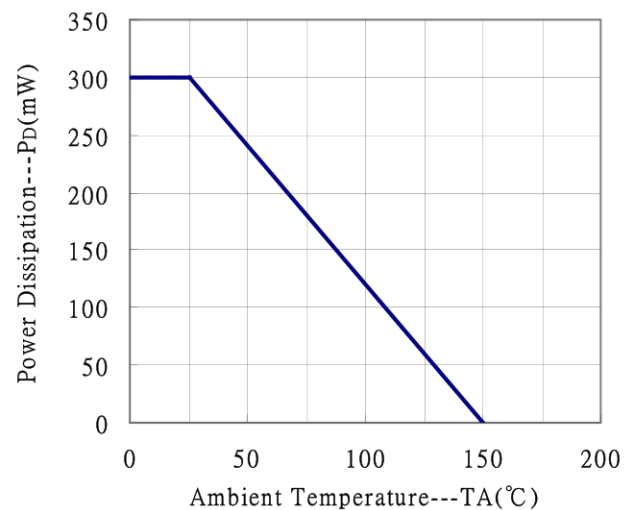
DYNAMIC IMPEDANCE vs FREQUENCY



OPEN-LOOP VOLTAGE GAIN vs FREQUENCY

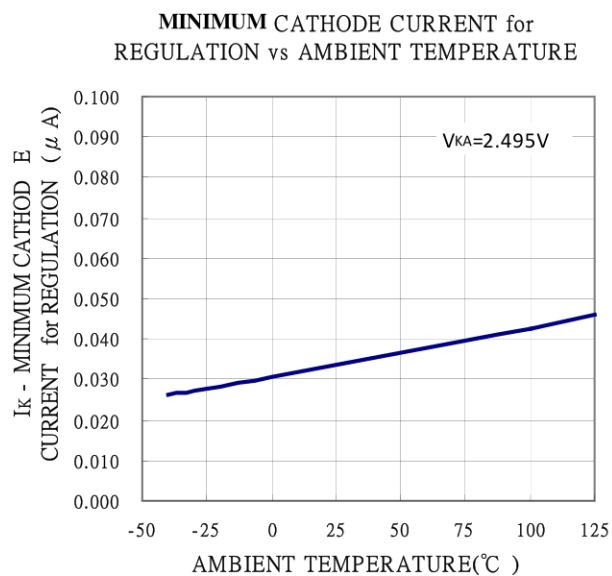
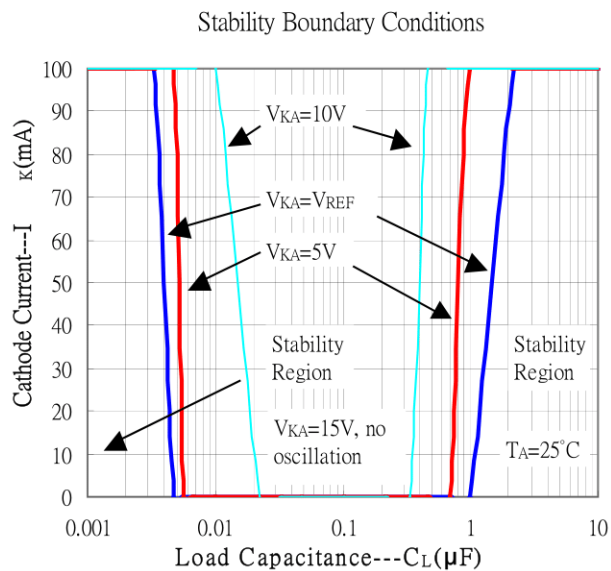


Power Derating Curve



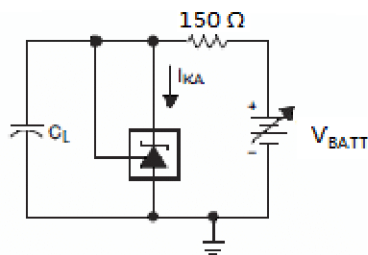
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Typical Characteristics(Cont.)

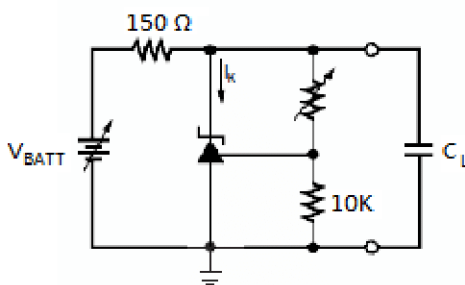


Test Circuit for Stability Boundary Conditions

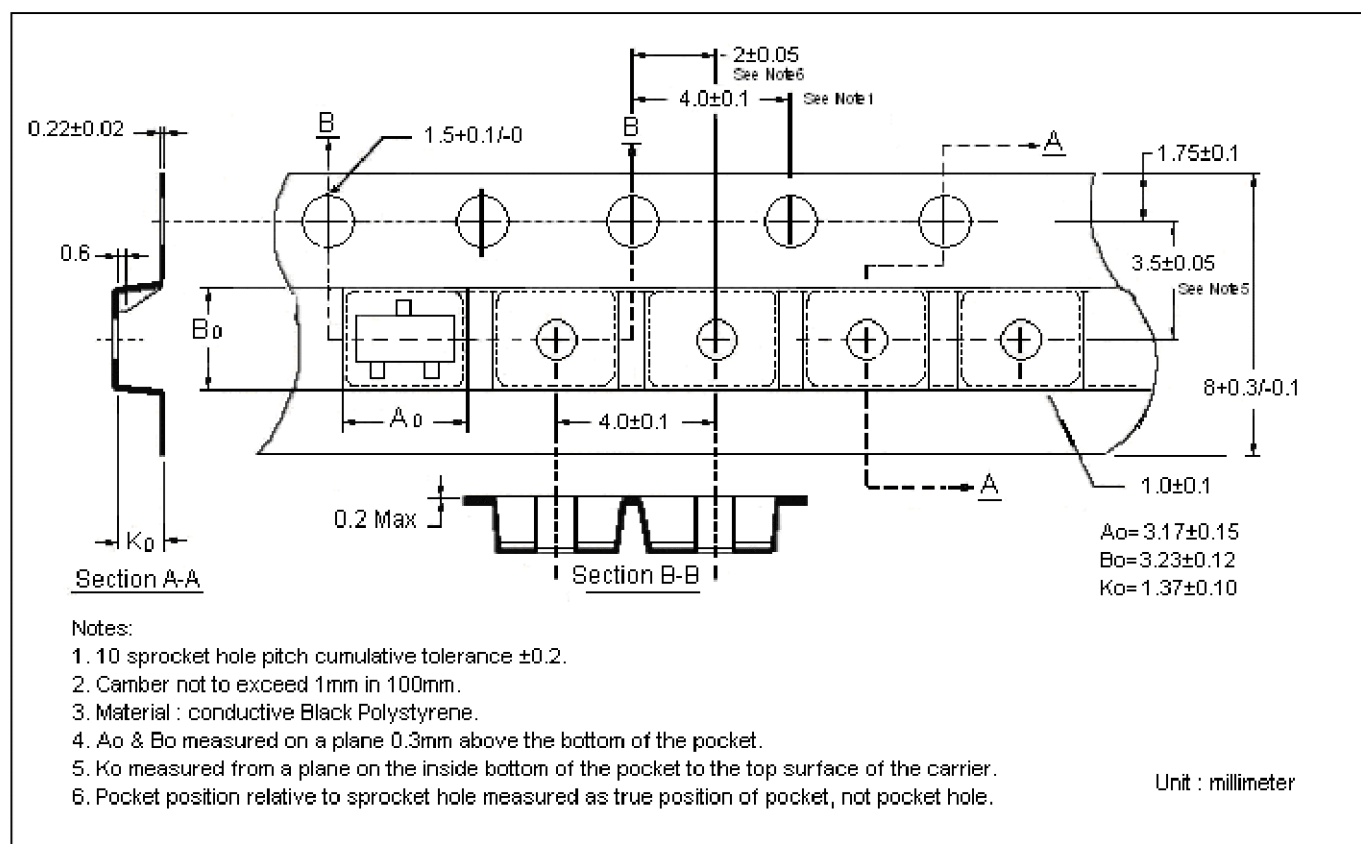
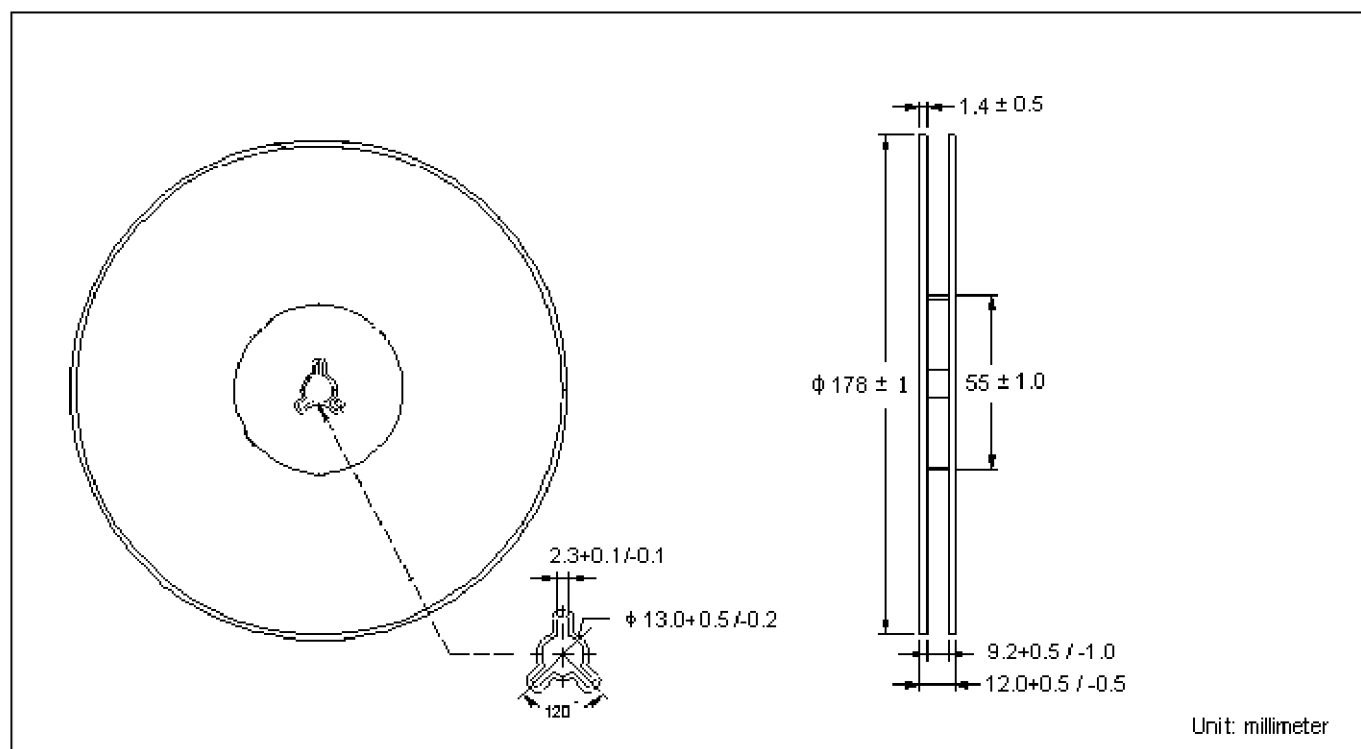
$V_{KA} = V_{REF}$



$V_{KA} = 5V, 10V, 15V$



※ C_L : MLCC capacitor

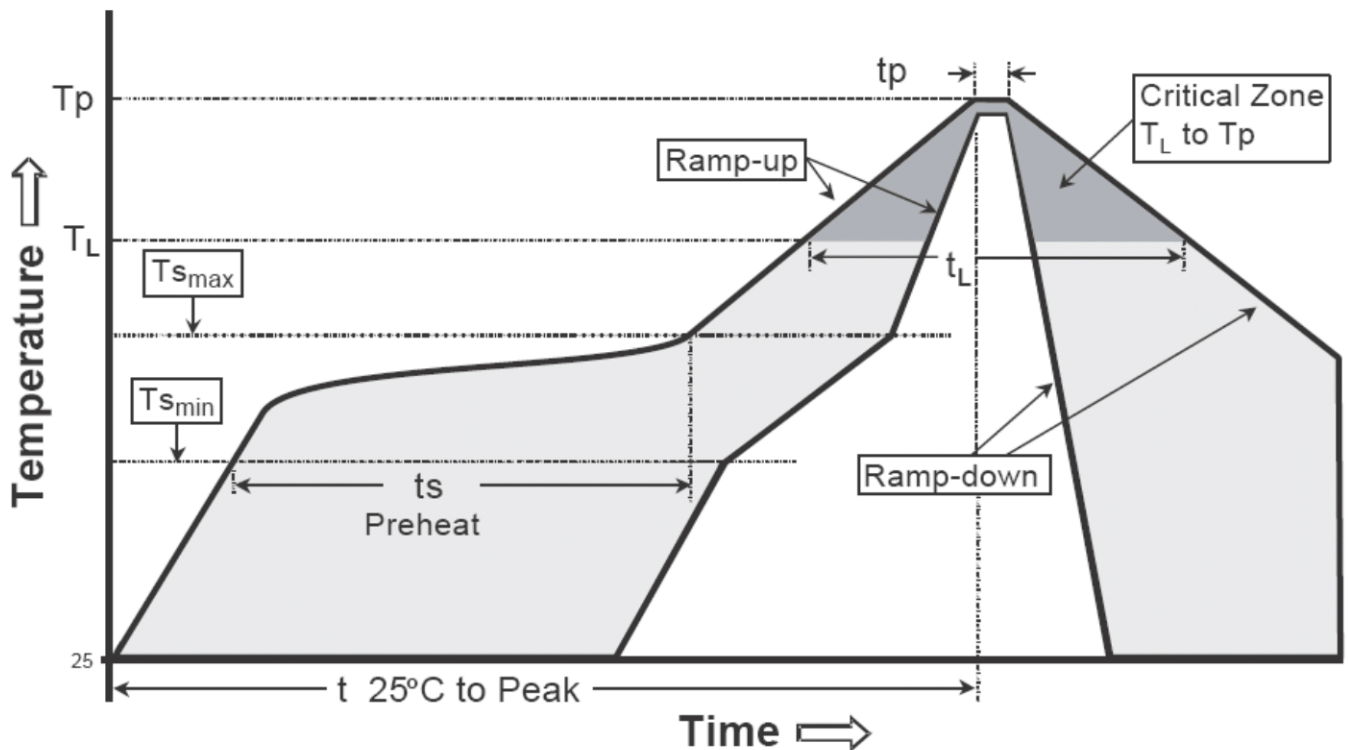




Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow

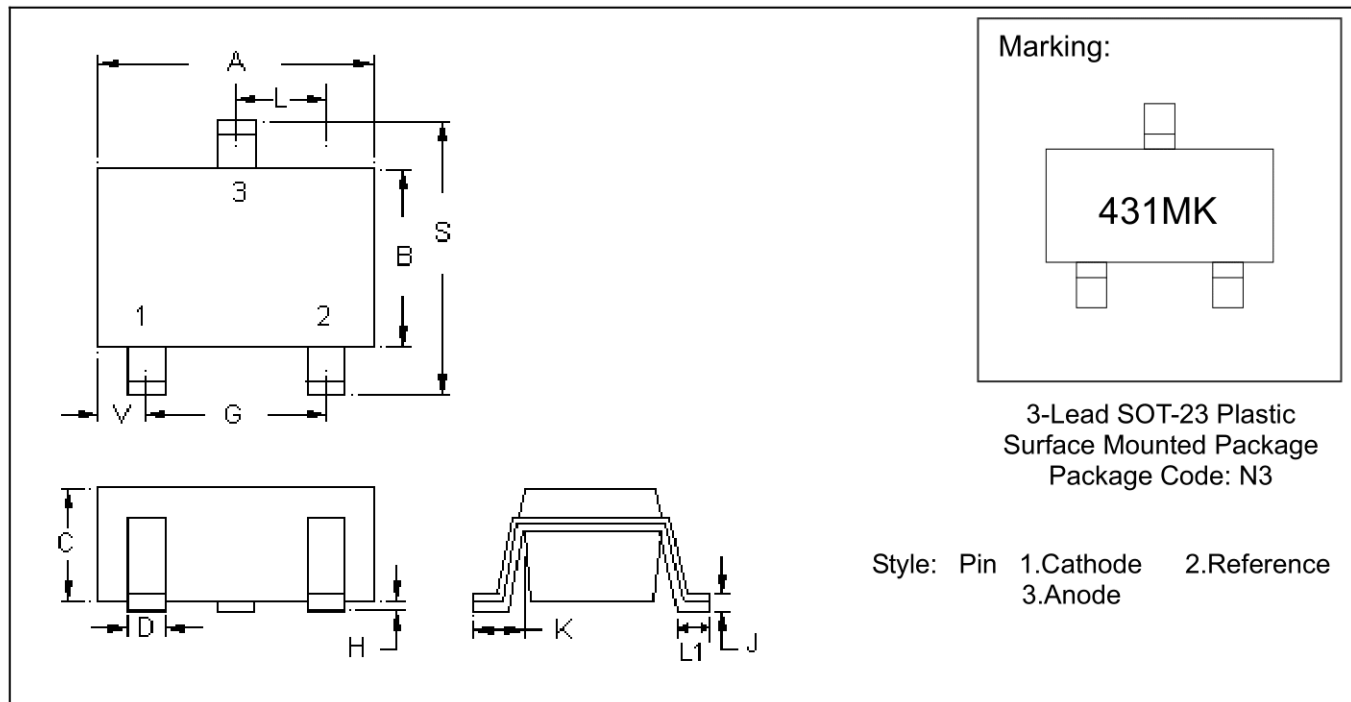


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate ($T_{s\max}$ to T_p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min($T_{s\min}$)	100°C	150°C
-Temperature Max($T_{s\max}$)	150°C	200°C
-Time($t_{s\min}$ to $t_{s\max}$)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T_L)	183°C	217°C
- Time (t_L)	60-150 seconds	60-150 seconds
Peak Temperature(T_p)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t_p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.



SOT-23 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0032	0.0079	0.08	0.20
B	0.0472	0.0669	1.20	1.70	K	0.0118	0.0266	0.30	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1161	2.10	2.95
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0000	0.0040	0.00	0.10	L1	0.0118	0.0197	0.30	0.50

Notes: 1. Controlling dimension: millimeters.

2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3. If there is any question with packing specification or packing method, please contact your local sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.